SPECIFICATIONS FOR NICHIA CHIP TYPE **UV** LED

MODEL : **NC4U133(T)**

NICHIA CORPORATION

1.SPECIFICATIONS

(1) Absolute Maximum Ratings (Ts=25°C)

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	I_F	700	mA
Pulse Forward Current	I_{FP}	1000	mA
Allowable Reverse Current	I_R	85	mA
Power Dissipation	P_D	12.1	W
Operating Temperature	T_{opr}	-10 ~ + 85	°C
Storage Temperature	T_{stg}	-40 ~ +100	°C
Dice Temperature	T_j	130	°C
Soldering Temperature	T_{sld}	Reflow Soldering : 260°C for 10sec.	

I_{FP} Conditions : Pulse Width ≤ 10msec. and Duty ≤ 1/10

(2) Initial Electrical/Optical Characteristics (Ts=25°C)

Item		Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage		V_F	I_F=500[mA]	-	(14.9)	17.3	V
Peak Wavelength	Rank Ua	λ_P	I_F=500[mA]	360	(365)	370	nm
Spectrum Half Width		$\triangle\lambda$	I_F=500[mA]	-	(9)	-	nm
Radiant Flux	Rank P8d33	ϕe	I_F=500[mA]	1010	-	1240	mW
	Rank P8d32			820	-	1010	
	Rank P8d31			670	-	820	

∗ Forward Voltage Measurement allowance is ± 0.14V.

∗ Radiant flux Values are traceable to the CIE 127:2007-compliant national standards.

∗ Radiant flux Measurement allowance is ±10%.

∗ Peak Wavelength Measurement allowance is ±3nm.

∗ Basically, a shipment shall consist of the LEDs of a combination of the above ranks.
The percentage of each rank in the shipment shall be determined by Nichia.

2.INITIAL OPTICAL/ELECTRICAL CHARACTERISTICS

Please refer to “CHARACTERISTICS” on the following pages.

3.OUTLINE DIMENSIONS AND MATERIALS

Please refer to “OUTLINE DIMENSIONS” on the following page.

4.PACKAGING

· The LEDs are packed in cardboard boxes after packaging in moisture proof foil bag.
Please refer to “PACKING” on the following pages.
The label on the minimum packing unit shows ; Part Number, Lot Number, Ranking, Quantity

(Taped Type)

· The LEDs are packed in cardboard boxes after taping.
Please refer to “TAPING DIMENSIONS” and “PACKING ”on the following pages.
The label on the minimum packing unit shows ; Part Number, Lot Number, Ranking, Quantity

· In order to protect the LEDs from mechanical shock, we pack them in cardboard boxes for transportation.
· The LEDs may be damaged if the boxes are dropped or receive a strong impact against them, so precautions must be taken to prevent any damage.
· The boxes are not water resistant and therefore must be kept away from water and moisture.
· When the LEDs are transported, we recommend that you use the same packing method as Nichia.

5.LOT NUMBER

The first six digits number shows **lot number**.
The lot number is composed of the following characters;

○□××××-◇◇◇

○ - Year (9 for 2009, A for 2010)
□ - Month (1 for Jan., 9 for Sep., A for Oct., B for Nov.)
×××× - Nichia's Product Number
◇◇◇ - Ranking by Wavelength, Ranking by Radiant flux

6.RELIABILITY

(1) TEST ITEMS AND RESULTS

Test Item	Standard Test Method	Test Conditions	Note	Number of Damaged
Resistance to Soldering Heat (Reflow Soldering)	JEITA ED-4701 300 301	Tsld=260°C, 10sec. (Pre treatment 30°C,70%,168hrs.)	2 times	0/10
Temperature Cycle	JEITA ED-4701 100 105	-40°C ~ 25°C ~ 100°C ~ 25°C 30min. 5min. 30min. 5min.	100 cycles	0/10
High Temperature Storage	JEITA ED-4701 200 201	Ta=100°C	1000hrs.	0/10
Low Temperature Storage	JEITA ED-4701 200 202	Ta=-40°C	1000hrs.	0/10
Steady State Operating Life Condition 1		Ta=25°C, I_F=500mA Tested with Nichia standard circuit board.*	1000hrs.	0/10
Steady State Operating Life Condition 2		Ta=25°C, I_F=700mA Tested with Nichia standard circuit board.*	1000hrs.	0/10
Steady State Operating Life of High Temperature		Ta=85°C, I_F=300mA Tested with Nichia standard circuit board.*	1000hrs.	0/10
Steady State Operating Life of High Humidity Heat		60°C, RH=90%, I_F=300mA Tested with Nichia standard circuit board.*	500hrs.	0/10
Steady State Operating Life of Low Temperature		Ta=-10°C, I_F=500mA Tested with Nichia standard circuit board.*	1000hrs.	0/10
Vibration	JEITA ED-4701 400 403	100 ~ 2000 ~ 100Hz Sweep 4min. 200m/s^2 3directions, 4cycles	48min.	0/10
Electrostatic Discharge	JEITA ED-4701 300 304	R=1.5kΩ, C=100pF Test Voltage=2kV	3 times Negative/Positive	0/10

* Thermal resistance of LED with Nichia standard circuit board : Rja ≒ 9°C/W

(2) CRITERIA FOR JUDGING DAMAGE

Item	Symbol	Test Conditions	Criteria for Judgement	
			Min.	Max.
Forward Voltage	V_F	I_F=500mA	-	Initial Level × 1.1
Radiant Flux	ϕe	I_F=500mA	Initial Level × 0.7	-

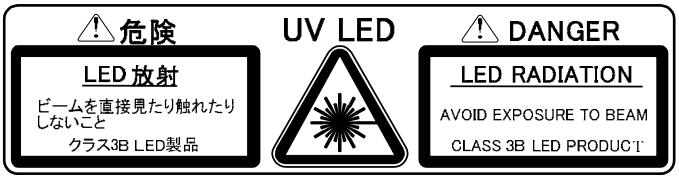
* The test is performed after the board is cooled down to the room temperature.

7.CAUTIONS

(1) Cautions

· The devices are UV light LEDs. The LED during operation radiates intense UV light, which precautions must be taken to prevent looking directly at the UV light with unaided eyes. Do not look directly into the UV light or look through the optical system. When there is a possibility to receive the reflection of light, protect by using the UV light protective glasses so that light should not catch one's eye directly.

· The caution label is attached to the moisture proof foil bag and cardboard box.



(2) Moisture Proof Package

· When moisture is absorbed into the SMT package it may vaporize and expand during soldering. There is a possibility that this can cause exfoliation of the contacts and damage the optical characteristics of the LEDs. For this reason, the moisture proof package is used to keep moisture to a minimum in the package.

· The moisture proof package is made of an aluminum moisture proof bag. A package of a moisture absorbent material (silica gel) is inserted into the aluminium moisture proof bag. The silica gel changes its color from blue to red as it absorbs moisture.

(3) Storage

· Storage Conditions

Before opening the package :

The LEDs should be kept at 30°C or less and 90%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material (silica gel) is recommended.

After opening the package :

The LEDs should be kept at 30°C or less and 70%RH or less. The LEDs should be soldered within 168 hours (7days) after opening the package. If unused LEDs remain, they should be stored in the moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.

· If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following condition.

Baking treatment : more than 24 hours at 65 ± 5°C

· Nichia LED electrodes are gold plated. The gold surface may be affected by environments which contain corrosive substances. Please avoid conditions which may cause the LED to corrode, tarnish or discolor. This corrosion or discoloration may cause difficulty during soldering operations. It is recommended that the customer use the LEDs as soon as possible.

· Please avoid rapid transitions in ambient temperature, especially in high humidity environments where condensation can occur.

(4) Static Electricity

· Static electricity or surge voltage damages the LEDs.
It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.

· All devices, equipment and machinery must be properly grounded. It is recommended that precautions be taken against surge voltage to the equipment that mounts the LEDs.

· When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a VF test at a lower current (below 1mA is recommended). The LEDs should be used the light detector etc. when testing the light-on. Do not stare into the LEDs when testing.

· Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current.

Criteria : (V_F > 8.0V at I_F=0.5mA)

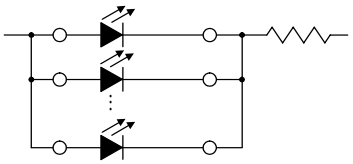
(5) Application Design Considerations

· Copper is recommended for the base metal of PCB to assemble the products.Thermal-mechanical stress during reflow soldering can cause glass breakage and/or solder cracking. Nichia strongly recommends that the customer thoroughly evaluate the assembly prior to use.

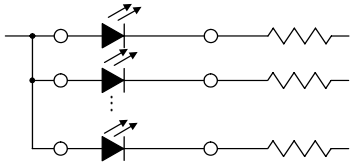
· This LED also emits visible light. Please take notice of visible light spectrum, in case you use this LED as light source of sensors etc.

· In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. It is recommended to use Circuit B which regulates the current flowing through each LED. In the meanwhile, when driving LEDs with a constant voltage in Circuit A, the current through the LEDs may vary due to the variation in forward voltage (V_F) of the LEDs. In the worst case, some LED may be subjected to stresses in excess of the absolute maximum rating.

(A)



(B)



· This product should be operated in forward bias. A driving circuit must be designed so that the product is not subjected to either forward or reverse voltage while it is off. In particular, if a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

· This product is intended to be used at or near its nominal drive current and characterized at the nominal current. It is not recommended to drive the LEDs at low current.

· After assembly and during use, the optical characteristics of the LED module can be affected by the corrosive gases emitted by components and materials in close proximity of the LEDs within an end product, and the gases entering into the product from the external atmosphere. The above should be taken into consideration when designing. Please note that resin materials, in particular, may contain halogen.

· Nichia makes the utmost efforts to improve the quality and reliability of its semiconductor products, however the failure and malfunction of a certain percentage is unavoidable due to their properties. As a responsibility of the Customer, sufficient measures should be given to ensuring safe design in Customer products, such as redundancy, fire-containment and anti-failure features to prevent accidents resulting in injury or death, fire or other social damage arising from these failure and malfunction.

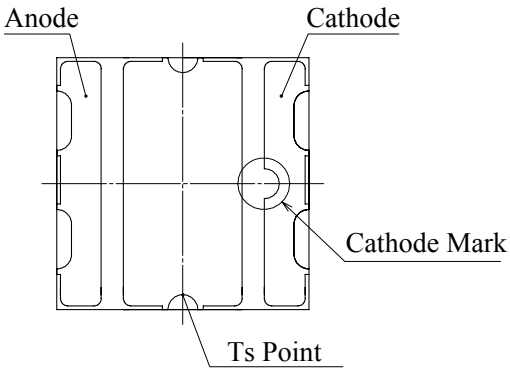
· Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum dice temperature (Tj).

· Please determine the operating current with consideration of the ambient temperature local to the LED and refer to the plot of Ambient temperature vs. Allowable Forward Current on CHARACTERISTICS in this specifications. Please also take measures to remove heat from the area near the LED to improve the operational characteristics of the LED.

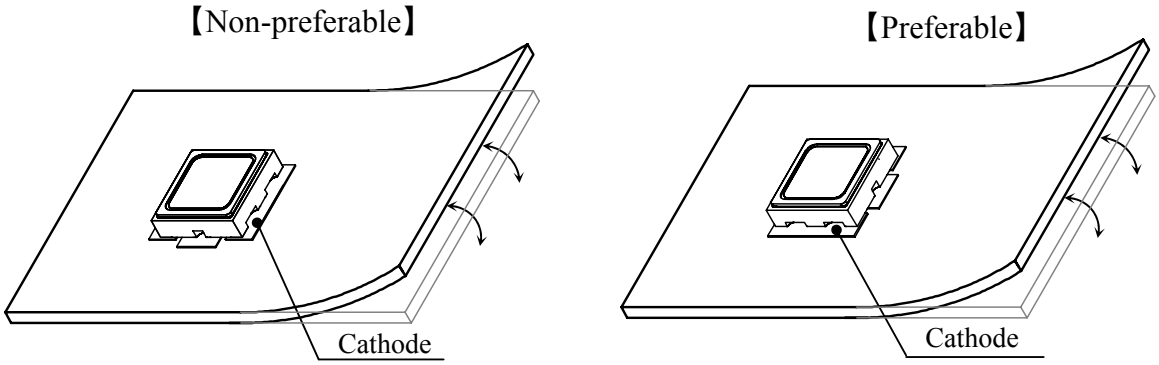
· The equation ① indicates correlation between Tj and Ta, and the equation ② indicates correlation between Tj and Ts.

$Tj=Ta + Rja \cdot W$ ····· ① $Tj=Ts + Rjs \cdot W$ ····· ②

∗Tj = Dice Temperature : °C, Ta = Ambient Temperature : °C, Ts = Solder Temperature : °C
Rja = Heat resistance from Dice to Ambient temperature : °C /W,
Rjs = Heat resistance from Dice to Ts measuring point : 4°C /W,
W = Inputting Power ($I_F \times V_F$) : W

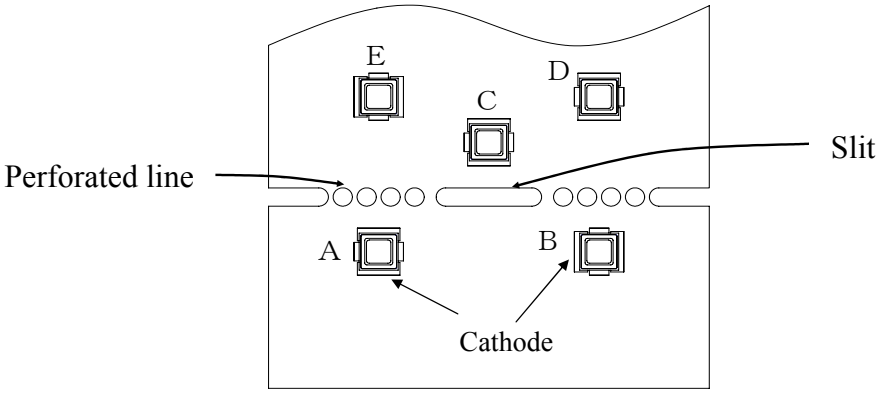


· Warpage of circuit board with soldered LEDs may result in damage, glass breakage and/or package breakage of the LEDs. Please pay special attention to the orientation of the LEDs as to avoid LED failure caused by bow, twist and warpage of the board.



When mechanical stress from the board affects the soldered LED, place the LED in the preferable location and orientation as shown above.

· Depending on the position and direction of LED, the mechanical stress on the LED package can be changed. Refer to the following figure.



Stress : A > B = C > D > E

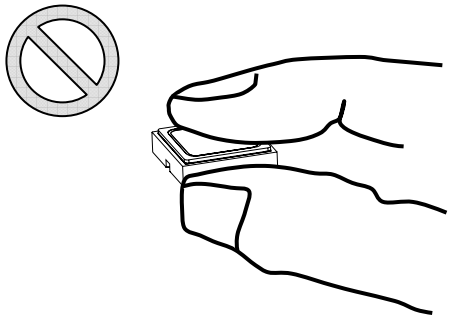
· When separating the circuit boards with soldered LEDs, please use appropriate tools and equipment. Hand brake without these tools and equipment may not be used.

(6) Handling Precautions

· The LEDs may be damaged if the these are dropped or receive a strong impact, so precautions must be taken to prevent any damage.

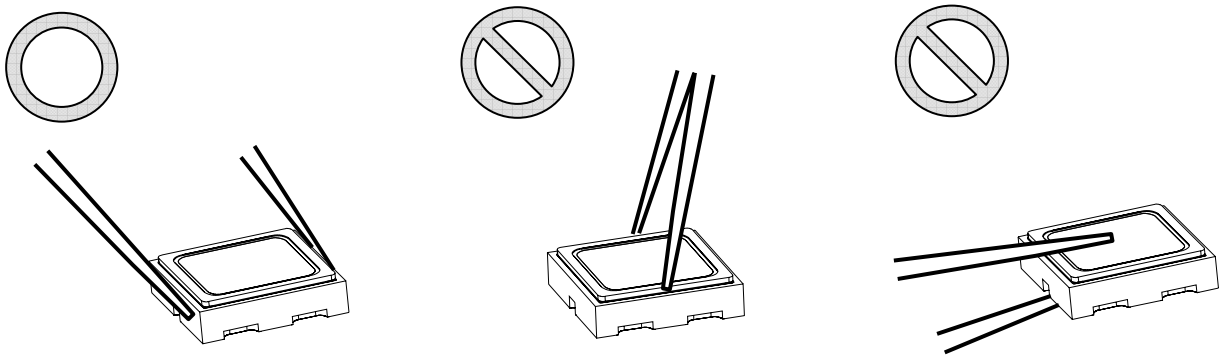
· Bare Hand

· When handling the product, touching the glass with bare hands will contaminate its surface that could affects on optical characteristics.



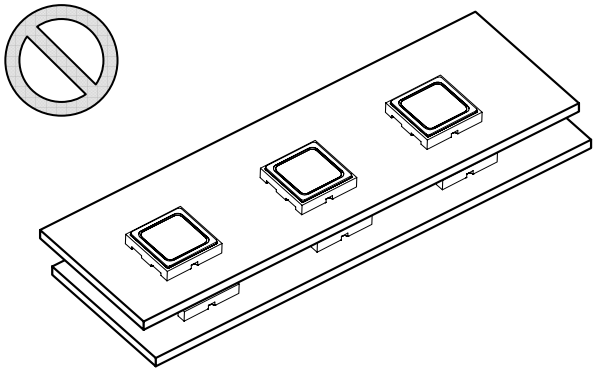
· Tweezers

· When handling it with tweezers, the product should only be held by the ceramics body, not by the glass. Failure to comply might result in glass breakage.



· Printed Circuit Board Assembled (PCB with LEDs soldered)

Do not stack assembled PCBs together. Stacking boards may cause the glasses of assembled LEDs to break due to the board stacked above.



(7) Soldering Conditions

· The LEDs can be soldered in place using the reflow soldering method. Nichia cannot make a guarantee on the LEDs after they have been assembled using the dip or hand soldering method.

· Recommended soldering conditions

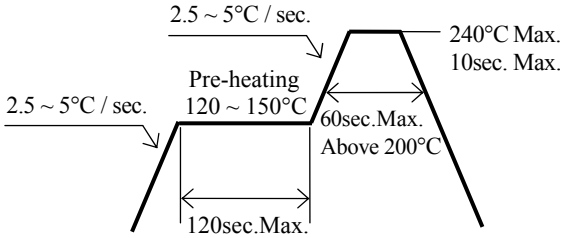
Reflow Soldering		
	Lead Solder	Lead-free Solder
Pre-heat	120 ~ 150°C	180 ~ 200°C
Pre-heat time	120 sec. Max.	120 sec. Max.
Peak temperature	240°C Max.	260°C Max.
Soldering time	10 sec. Max.	10 sec. Max.
Condition	refer to Temperature - profile ①.	refer to Temperature - profile ②. (N_2 reflow is recommended.)

∗ Although the recommended soldering conditions are specified in the above table, reflow soldering at the lowest possible temperature is desirable for the LEDs.

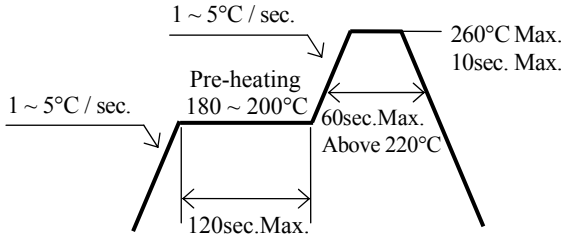
∗ A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

[Temperature-profile (Surface of circuit board)] Use the conditions shown to the under figure.

<① : Lead Solder>

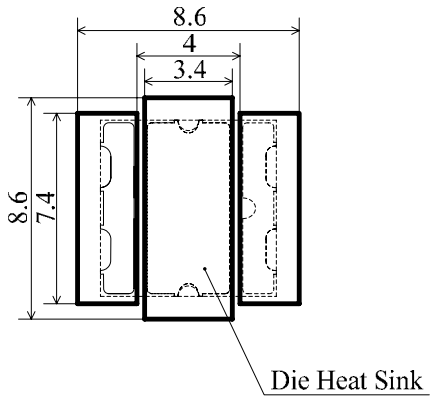


<② : Lead-free Solder>



[Recommended soldering pad design] Use the following conditions shown in the figure.

The product has a floating die heat sink. Please make sure that the die heat sink is soldered for proper heat dissipation.



(Unit : mm)

· Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the customer use the nitrogen reflow method.

· Repairing should not be done after the LEDs have been soldered. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

· Reflow soldering should not be done more than two times.

· When soldering, do not put stress on the LEDs during heating.

(8) Cleaning

· The LED module should not be cleaned, washed or soaked in water or solvent.
Some cleaning agents attack or dissolve the package and the glass. Care must be taken to ensure that no problems are encountered with the use of the solvents.
Freon solvents should not be used to clean the LEDs because of worldwide regulations.
· Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Before cleaning, a pre-test should be done to confirm whether any damage to the LEDs will occur.

(9) Safety Guideline for Human Eyes

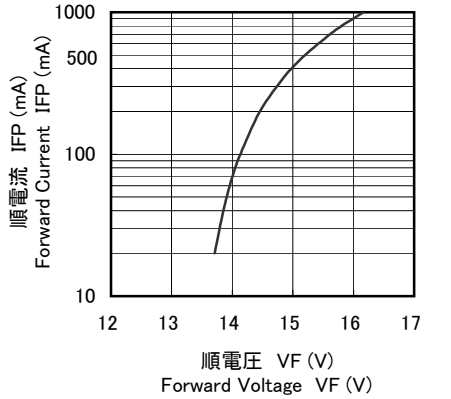
· The International Electrical Commission (IEC) published in 2006 IEC 62471:*2006 Photobiological safety of lamps and lamp systems* which includes LEDs within its scope. Meanwhile LEDs were removed from the scope of the IEC 60825-1:2007 laser safety standard, the 2001 edition of which included LED sources within its scope. However, keep in mind that some countries and regions have adopted standards based on the IEC laser safety standard IEC 60825-1:2001 which includes LEDs within its scope.
Following IEC 62471:2006, most of Nichia LEDs can be classified as belonging to either Exempt Group or Risk Group 1. Optical characteristics of a LED such as radiant flux, spectrum and light distribution are factors that affect the risk group determination of the LED. Especially a high-power LED, that emits light containing blue wavelengths, may be in Risk Group 2.
Great care should be taken when viewing directly the LED driven at high current or the LED with optical instruments, which may greatly increase the hazard to your eyes.

(10) Others

· NC4U133 complies with RoHS Directive.
· The LEDs described in this brochure are intended to be used for ordinary electronic equipment (such as office equipment, communications equipment, measurement instruments and household appliances). Consult Nichia's sales staff in advance for information on the applications in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as for airplanes, aerospace, submersible repeaters, nuclear reactor control systems, automobiles, traffic control equipment, life support systems and safety devices).
· The customer shall not reverse engineer by disassembling or analysis of the LEDs without having prior written consent from Nichia. When defective LEDs are found, the customer shall inform Nichia directly before disassembling or analysis.
· The formal specifications must be exchanged and signed by both parties before large volume purchase begins.
· The appearance and specifications of the product may be modified for improvement without notice.

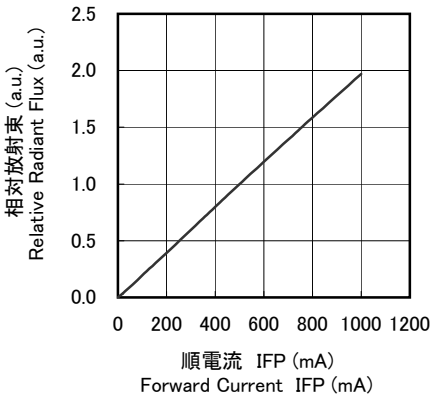
■ 順電圧－順電流特性
Forward Voltage vs.
Forward Current

Ta=25℃



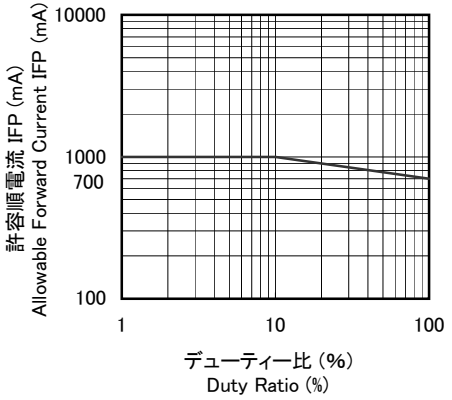
■ 順電流-相対放射束特性
Forward Current vs.
Relative Radiant Flux

Ta=25℃



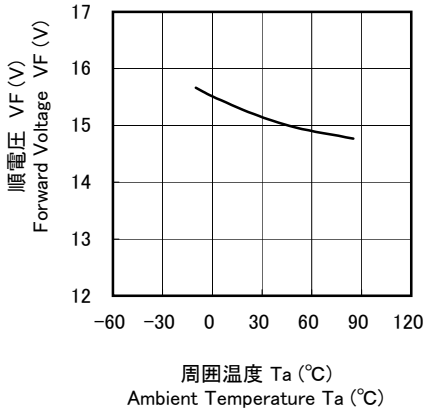
■ デューティー比－許容順電流特性
Duty Ratio vs.
Allowable Forward Current

Ta=25℃



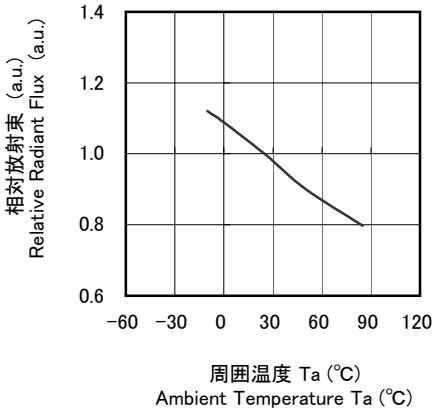
■ 周囲温度-順電圧特性
Ambient Temperature vs.
Forward Voltage

IFP=500mA



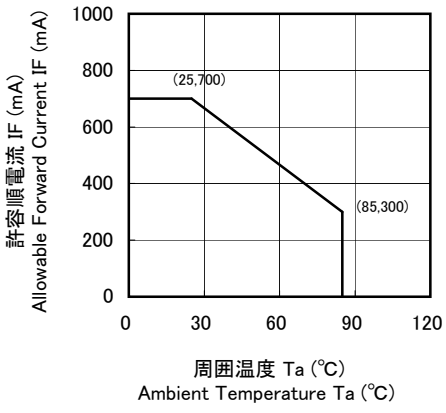
■ 周囲温度-相対放射束特性
Ambient Temperature vs.
Relative Radiant Flux

IFP=500mA



■ 周囲温度-許容順電流特性
Ambient Temperature vs.
Allowable Forward Current

Rja=9℃/W

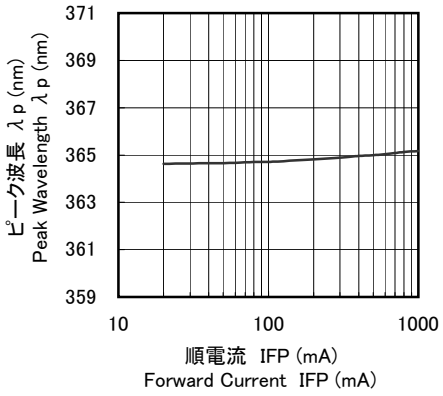


型名 Model NC4U133	名称 Title 初期電気/光学特性 CHARACTERISTICS
日亜化学工業（株） NICHIA CORPORATION	管理番号 No. 100112945771

Nichia STS-DA1-0892A
<Cat.No.100312>

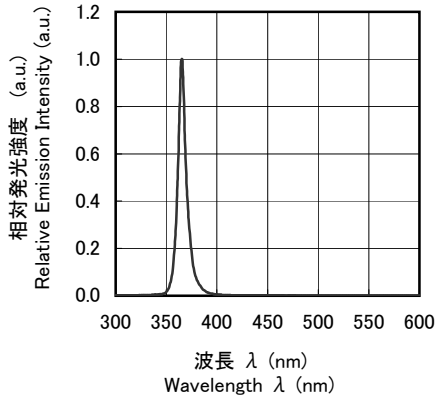
■ 順電流-ピーク波長特性
Forward Current vs.
Peak Wavelength

Ta=25℃



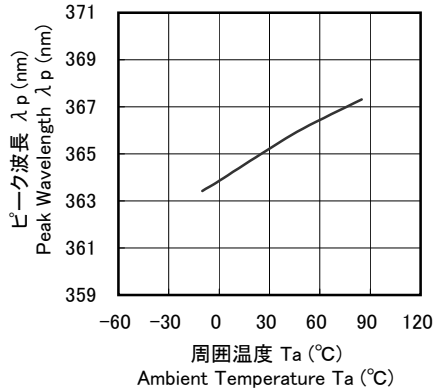
■ 発光スペクトル
Spectrum

Ta=25℃
IFP=500mA



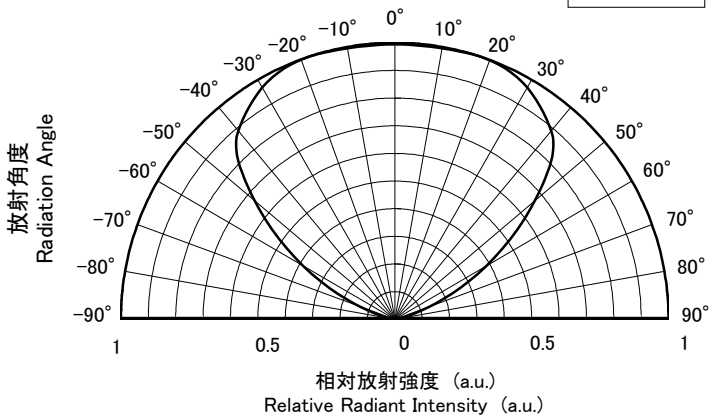
■ 周囲温度-ピーク波長特性
Ambient Temperature vs.
Peak Wavelength

IFP=500mA



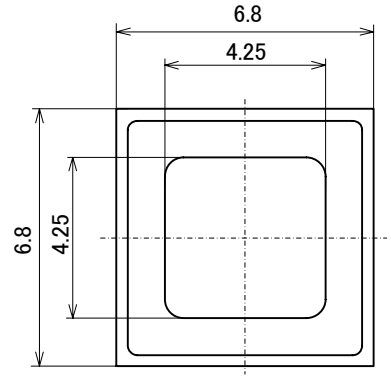
■ 指向特性
Directivity

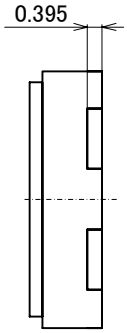
Ta=25℃
IFP= 500mA

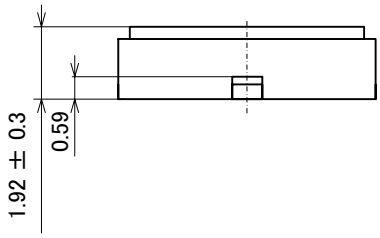


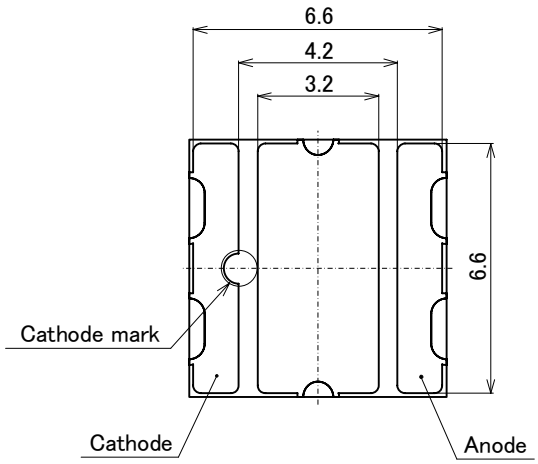
型名 Model	名称 Title
NC4U133	初期電気/光学特性 CHARACTERISTICS
日亜化学工業（株） NICHIA CORPORATION	管理番号 No. 100112945781

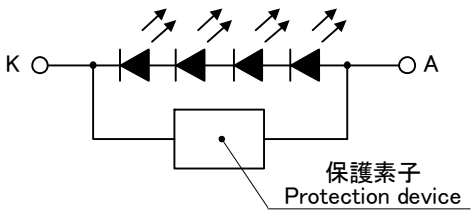
Nichia STS-DA1-0892A
<Cat.No.100312>







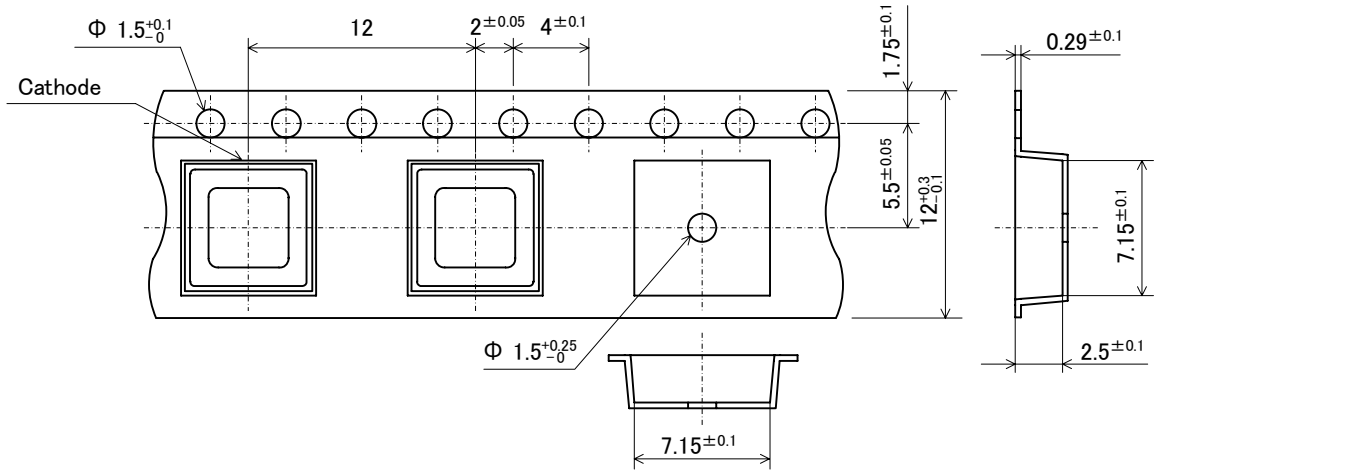


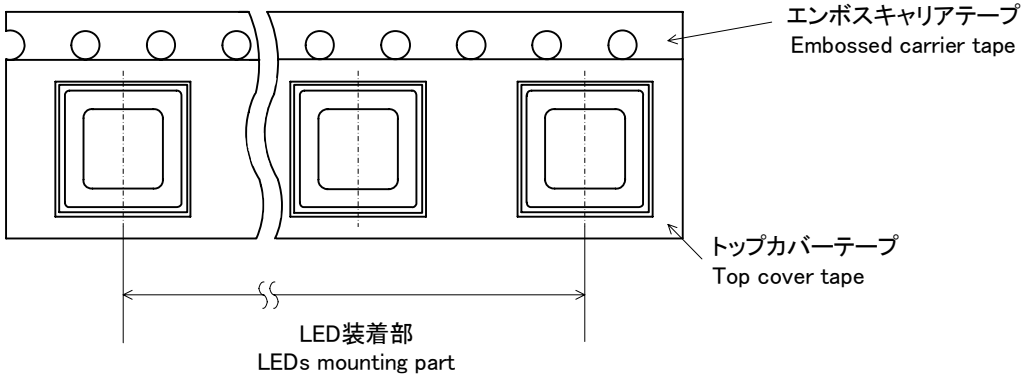


項目 Item	材質 Materials
パッケージ材質 Package	セラミックス Ceramics
ガラス窓 Glass	硬質ガラス / コバール Hard Glass / Kovar
電極 Electrodes	金メッキ Au Plating
ダイヒートシンク Die Heat Sink	金メッキ Au Plating

（注）　本製品には静電気に対する保護素子が内蔵されています。
(NOTE) NC4U13x has a protection device built in as a protection circuit against static electricity.

型名 Model	名称	単位 Unit
NC4U13x	Title 外形寸法図 OUTLINE DIMENSIONS	mm
日亜化学工業（株） NICHIA CORPORATION	管理番号 No. 100310945793	公差 Allow ±0.2



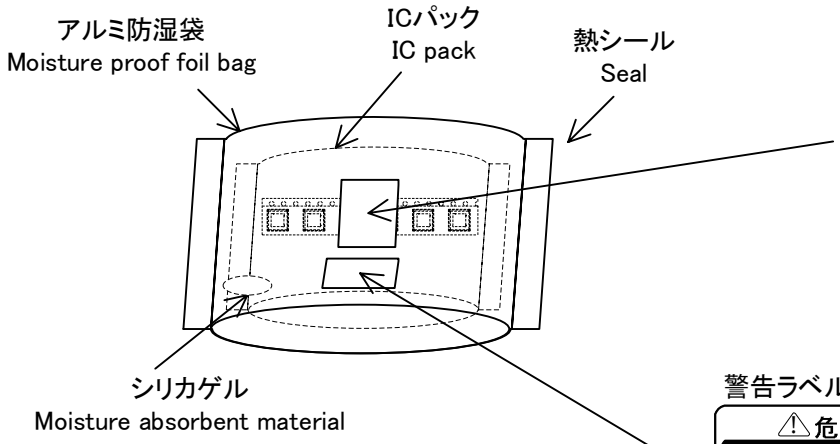


数量 100個入/袋
Quantity 100pcs/Pack

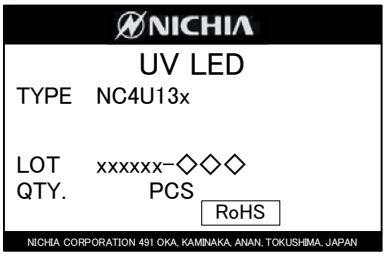
型名 Model NC4U13x	名称 Title 梱包仕様図 PACKING	単位 Unit mm
日亜化学工業（株） NICHIA CORPORATION	管理番号 No. 090709945801	

Nichia STS-DA1-0892A
<Cat.No.100312>

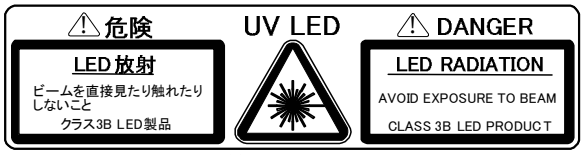
シリカゲルとともにICパックをアルミ防湿袋に入れ、熱シールにより封をする。
The IC pack and moisture absorbent material are put in the moisture proof foil bag and then heat sealed.



ラベル Label

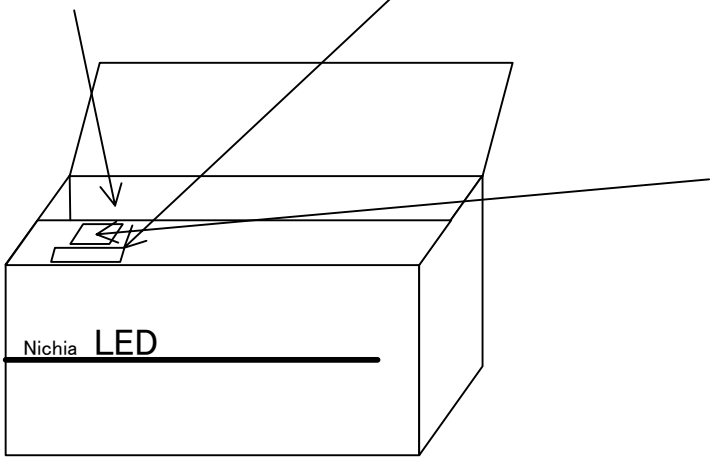


警告ラベル Caution Label

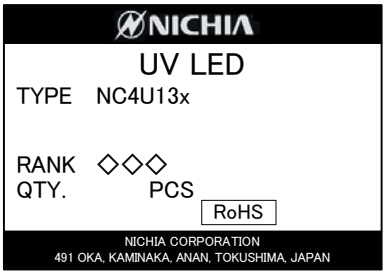


＊アルミ防湿袋、外箱に貼り付け
This Caution Label is applied on Moisture proof foil bag and on Cardboard box.

間隔にはクッション材を詰める
Empty space in the box is filled with cushion material.



ラベル Label



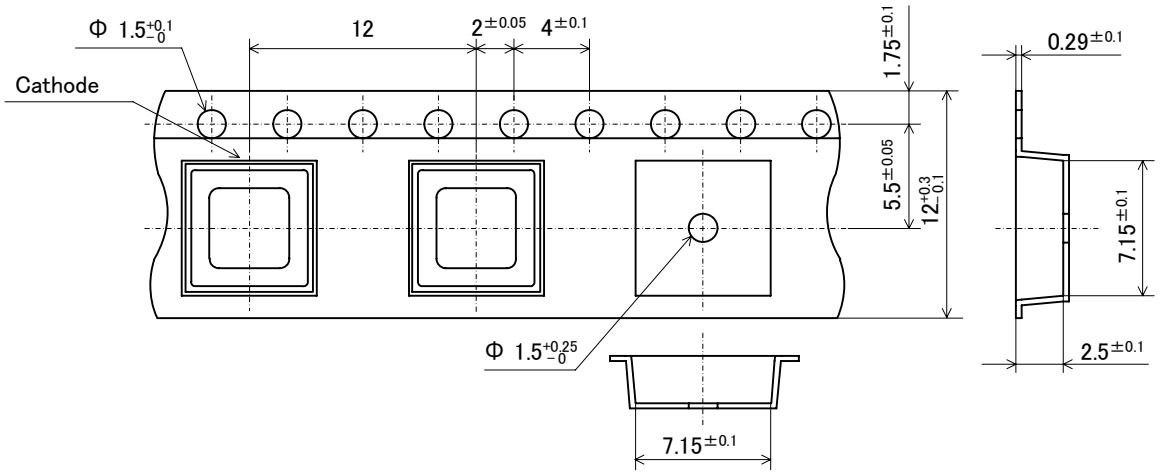
基本梱包単位 Packing Unit

	チップ個数 Quantity/bag(pcs)
アルミ防湿袋 Moisture proof foil bag	100 MAX.

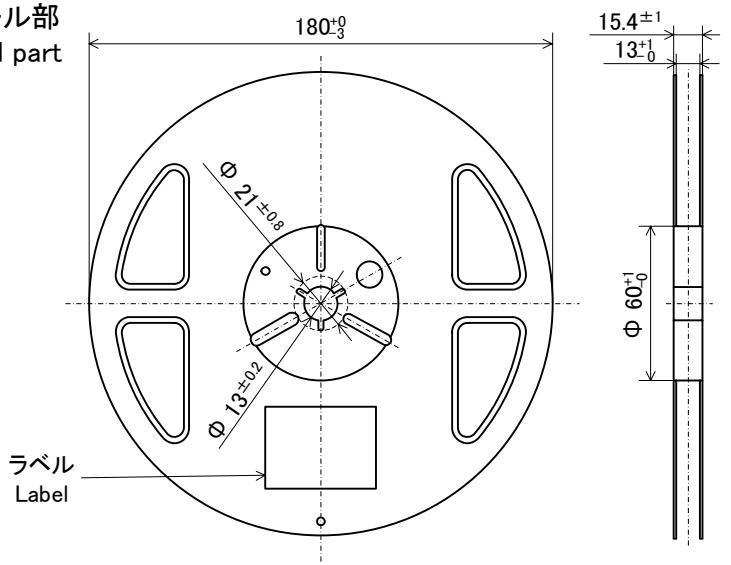
梱包箱(段ボール) Cardbord box	箱の寸法 Dimensions(mm)	袋数 Bag/box	チップ個数 Quantity/box(pcs)
S	250×140×90×4t	5bag MAX.	500 MAX.

型名 Model NC4U13x	名称 Title	梱包仕様図 PACKING
日亜化学工業（株） NICHIA CORPORATION	管理番号 No.	100112945811

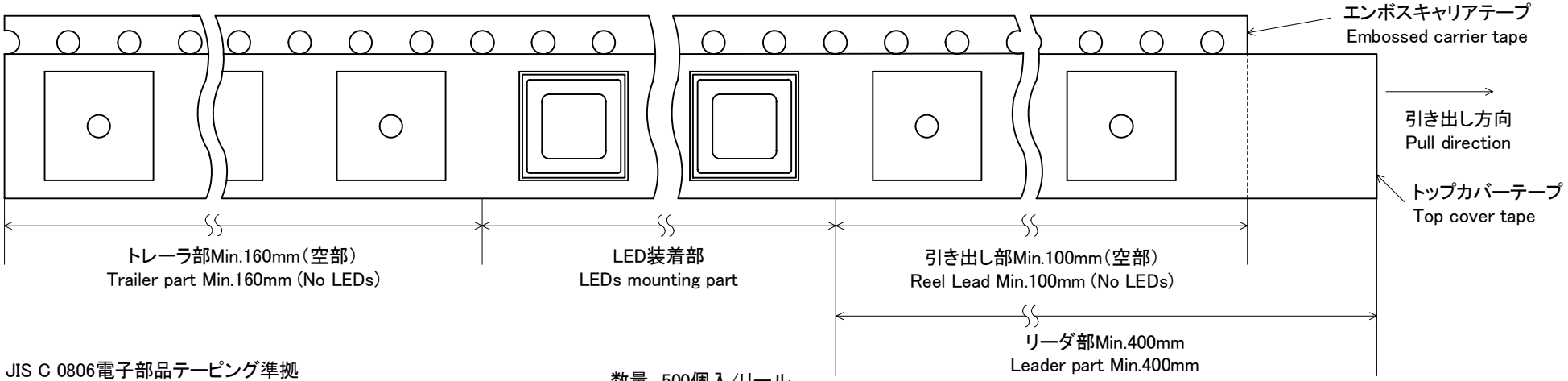
テーピング部 Taping part



リール部 Reel part



トレーラ部/リーダ部 Trailer Part/Leader Part



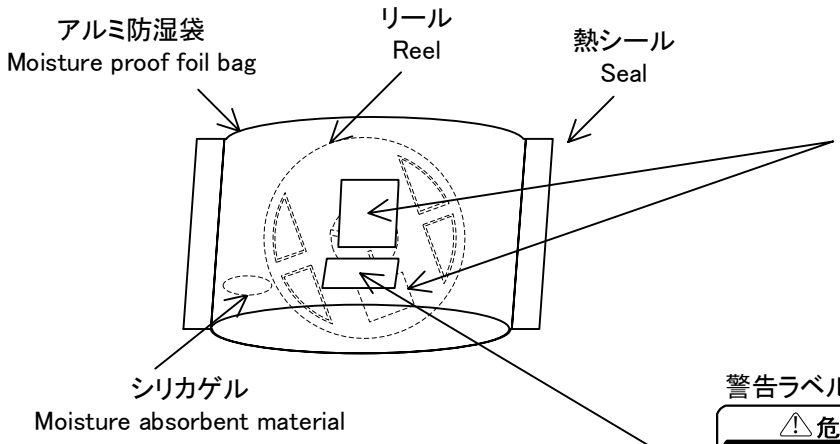
JIS C 0806電子部品テーピング準拠
Taping is based on the JIS C 0806 : Packaging of Electronic Components on Continuous Tapes.

数量 500個入/リール
Quantity 500pcs/Reel

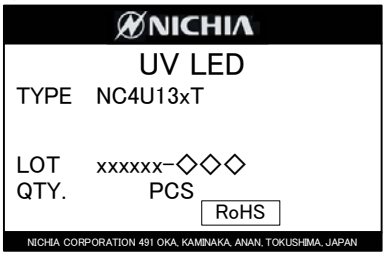
型名 Model NC4U13xT	名称 Title テーピング仕様図 TAPING DIMENSIONS	単位 Unit mm
日亜化学工業（株） NICHIA CORPORATION	管理番号 No. 100112945821	

Nichia STS-DA1-0892A
<Cat.No.100312>

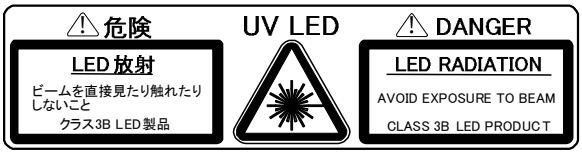
シリカゲルとともにリールをアルミ防湿袋に入れ、熱シールにより封をする。
The reel and moisture absorbent material are put in the moisture proof foil bag and then heat sealed.



ラベル Label

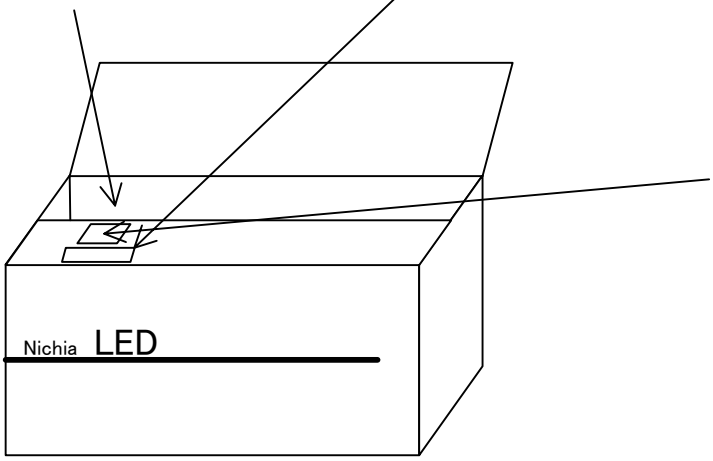


警告ラベル Caution Label

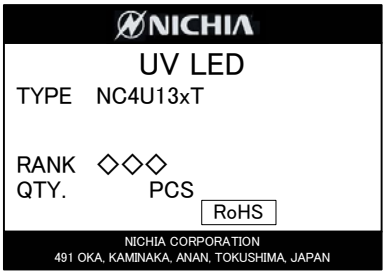


＊アルミ防湿袋、外箱に貼り付け
This Caution Label is applied on Moisture proof foil bag and on Cardboard box.

ダンボールで仕切りをする
The box is partitioned with the cardboard.



ラベル Label



基本梱包単位 Packing Unit

	リール数 Reel/bag	チップ個数 Quantity/bag(pcs)
アルミ防湿袋 Moisture proof foil bag	1reel	500 MAX.

梱包箱(段ボール) Cardbord box	箱の寸法 Dimensions(mm)	リール数 Reel/box	チップ個数 Quantity/box(pcs)
S	291×237×120×8t	5reel MAX.	2,500 MAX.
M	259×247×243×5t	10reel MAX.	5,000 MAX.
L	444×262×259×8t	20reel MAX.	10,000 MAX.

型名 Model NC4U13xT	名称 Title	梱包仕様図 PACKING
日亜化学工業（株） NICHIA CORPORATION	管理番号 No.	100112945831